

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application:

Listing of Claims:

Claims 1-12 (cancelled)

Claim 13 (original) A semiconductor device comprising:

a substrate having a substantially planar surface and an interior sloped surface;
a wettable layer adhered to a portion of the interior sloped surface; and
a solder layer adhered to a first portion of the wettable layer.

Claim 14 (original) The semiconductor device of claim 13, wherein the wettable layer comprises a metal.

Claim 15 (original) The semiconductor device of claim 13, further comprising a coating layer adhered to a second portion of the wettable layer.

Claim 16 (original) The semiconductor device of claim 15, wherein the coating layer is a non-wettable layer.

Claim 17 (original) The semiconductor device of claim 16, wherein the coating layer comprises a dielectric material.

Claim 18 (original) The semiconductor device of claim 13, wherein the solder layer comprises a tin-bismuth compound.

Claim 19 (original) The semiconductor device of claim 13, wherein the solder layer comprises a eutectic tin-lead compound.

Claim 20 (original) The semiconductor device of claim 13, further comprising a rigid organic film adhered to a portion of the substantially planar surface of the substrate and adjacent to a portion of the sloped surface.

Claims 21-28 (cancelled)